



America Semiconductor

Silicon Bridge Rectifier

GBPC2506TW thru GBPC2510TW

$V_{RRM} = 50\text{ V} - 1000\text{ V}$

$I_F = 25\text{ A}$

Features

- Integrally molded heat sink provides low thermal resistance for maximum heat dissipation
- Types up to 1000 V V_{RRM}
 - Void-free junction by using vacuum soldering
- High surge current capability
- High temperature soldering guaranteed: 260°C/ 10 seconds at 5 lbs(2.3 kg) tension
- Universal 3-way terminals: snap on, wire-around, or P.C board mounting

Mechanical Data

Case: Molded plastic with heat sink mounted in the bridge

Mounting position: Bolt down on heat-sink with silicone thermal compound between bridge and mounting surface

Terminals: Either nickel plated 0.25"(6.35 mm) Faston lugs or 0.040"(1.02 mm) diameter copper leads.

Weight: 15 grams or 0.53 ounces

Mounting torque: 20 inch-lbs max

Polarity: Marked on body

GBPC-T/W Package



Maximum ratings, at $T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified (GBPCXXXXT uses GBPC-T package while GBPCXXXXW uses GBPC-W package)

Parameter	Symbol	Conditions	GBPC2506T/W	GBPC2508T/W	GBPC2510T/W	Unit
Repetitive peak reverse voltage	V_{RRM}		600	800	1000	V
RMS reverse voltage	V_{RMS}		420	560	700	V
DC blocking voltage	V_{DC}		600	800	1000	V
Continuous forward current	I_F	$T_C \leq 50\text{ }^{\circ}\text{C}$	25	25	25	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25\text{ }^{\circ}\text{C}$, $t_p = 8.3\text{ ms}$	300	300	300	A
Operating temperature	T_j		-55 to 150	-55 to 150	-55 to 150	$^{\circ}\text{C}$
Storage temperature	T_{stg}		-55 to 150	-55 to 150	-55 to 150	$^{\circ}\text{C}$

Electrical characteristics, at $T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	GBPC2506T/W	GBPC2508T/W	GBPC2510T/W	Unit
Diode forward voltage	V_F	$I_F = 12.5\text{ A}$, $T_j = 25\text{ }^{\circ}\text{C}$	1.1	1.1	1.1	V
Reverse current	I_R	$V_R = 50\text{ V}$, $T_j = 25\text{ }^{\circ}\text{C}$ $V_R = 50\text{ V}$, $T_j = 125\text{ }^{\circ}\text{C}$	5 500	5 500	5 500	μA

Thermal characteristics

Thermal resistance, junction - case	R_{thJC}		1.9	1.9	1.9	$^{\circ}\text{C/W}$
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FIG.5-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS PER LEG

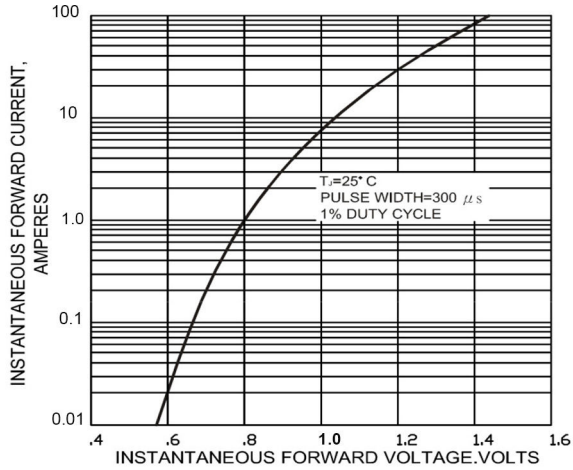


FIG.6-TYPICAL REVERSE LEAKAGE CHARACTERISTICS PER LEG

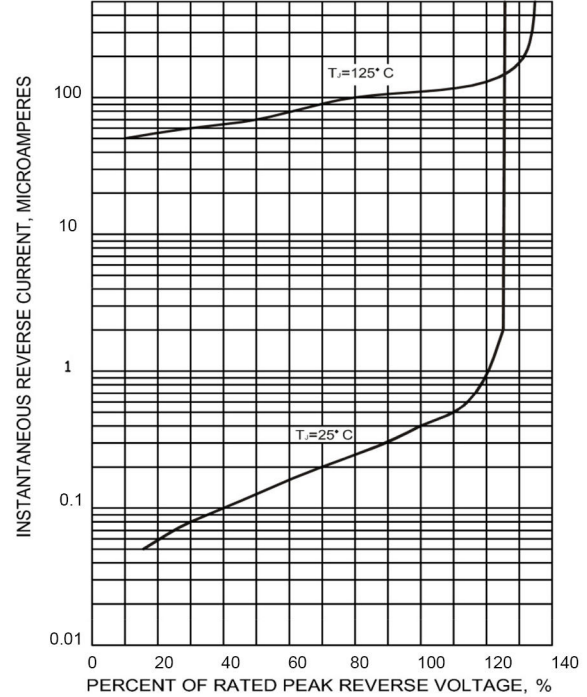


FIG.7-TYPICAL JUNCTION CAPACITANCE PER LEG

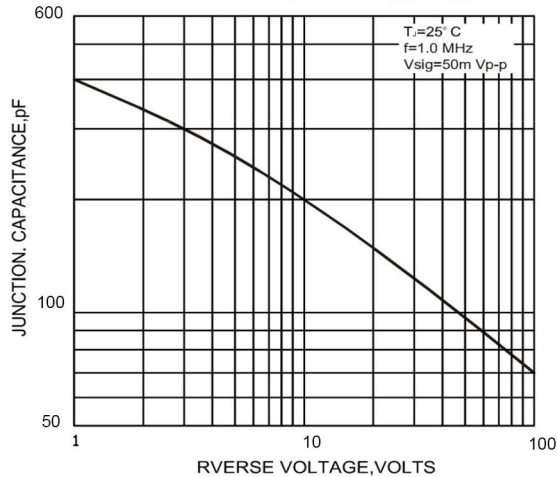
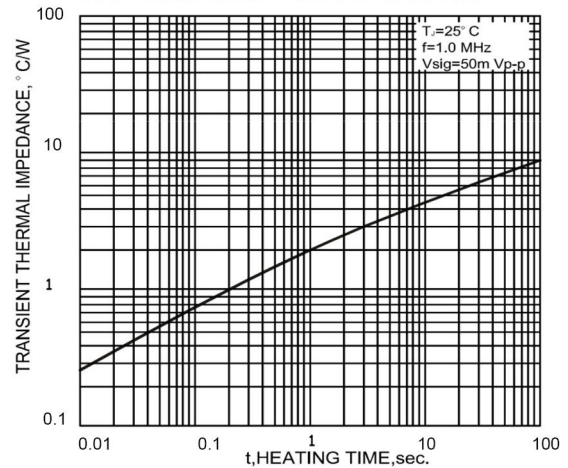


FIG.8-TYPICAL TRANSIENT THERMAL IMPEDANCE PER LEG



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